

Wafer Edge Inspection Data Gathering

Abstract of the Disclosure

A wafer edge inspection method and apparatus include a review tool that captures images of the semiconductor wafer. According to various embodiments, the present invention also includes a map of points of interest proximate to the edge of the wafer, automatic image capturing at the points of interest, fake defect locations defining the points of interest, a database in which the images are stored and computer-searchable for detailed defect analysis, a software tool for controlling the method and apparatus and/or context information identifying the points of interest, the inspected wafer and/or the fabrication station/step preceding the inspection.